IN THE CLAIMS

This listing of the claim will replace all prior versions and listings of claim in the present application.

Listing of Claims

Claims 1-4 (canceled).

5. (Currently Amended) The fitting substrate for connection to which first and second kinds of signal processing substrates mutually transmitting and receiving signals are fitted, comprising:

a substrate main body;

first signal connection point groups formed on said substrate main body and connected to said first kind of signal processing substrate;

second signal connection point groups formed on said substrate main body and connected to said second kind of signal processing substrate; and

wiring pattern groups for electrically connecting mutually corresponding signal connection points of said first and second signal connection point groups to one another,

wherein said first and second signal connection point groups are respectively formed so that mutually corresponding signal connection points can be arranged substantially horizontally on the same plane, and said wiring pattern group is formed substantially linearly to match with the arrangement of each of said signal connection points~~as defined in claim 4~~,

wherein said first and second signal connection point groups are so formed on the same plane so as to extend in a first direction and said wiring pattern groups are formed as to extend in a second direction intersecting orthogonally said first direction,

wherein N1 of said first kind of signal processing substrate and N2 of said second kind of signal processing substrate are fitted to said substrate main body,

wherein said first signal connection point groups are constituted by N2 of signal path groups adjacent to one another in said second direction and said second signal connection point groups are constituted by N1 of signal path groups adjacent to one another in said second direction,

wherein said substrate main body is formed into multiple layers and said wiring pattern groups are constituted by a plurality of wiring layers that form said substrate main body, and

wherein said first signal connection point group ~~is~~are constituted by a plurality of first signal connection rows adjacent to one another in said second direction, said second signal connection point ~~group is~~ groups are constituted by a plurality of second signal connection rows adjacent to one another in said second direction, and each of said connection groups constituted by at least one of said first signal connection rows and at least one of said second signal connection rows is connected by said wiring pattern ~~group~~ groups by using different ones of said wiring layers.

6. (Currently Amended) ~~The~~ A fitting substrate for connection to which first and second kinds of signal processing substrates mutually transmitting and receiving signals are fitted, comprising:

a substrate main body;

first signal connection point groups formed on said substrate main body and connected to said first kind of signal processing substrate;

second signal connection point groups formed on said substrate main body and connected to said second kind of signal processing substrate; and

wiring pattern groups for electrically connecting mutually corresponding signal connection points of said first and second signal connection point groups to one another,

wherein said first and second signal connection point groups are respectively formed so that mutually corresponding signal connection points can be arranged substantially horizontally on the same plane, and said wiring pattern group is formed substantially linearly to match with the arrangement of each of said signal connection points,

wherein said first and second signal connection point groups are so formed on the same plane so as to extend in a first direction and said wiring pattern groups are formed as to extend in a second direction intersecting orthogonally said first direction,

wherein N1 of said first kind of signal processing substrate and N2 of said second kind of signal processing substrate are fitted to said substrate main body,

wherein said first signal connection point groups are constituted by N2 of signal path groups adjacent to one another in said second direction and said second signal connection point groups are constituted by N1 of signal path groups adjacent to one another in said second direction,

wherein said substrate main body is formed into multiple layers and said wiring pattern groups are constituted by a plurality of wiring layers that form said substrate main body, and~~as defined in claim 4,~~

wherein said N2 of ~~said~~ signal path groups of each of said signal processing substrates is connected by said wiring pattern ~~group~~ groups by using different ones of said wiring layers.

Claims 7-10 (canceled).